

In the claims:

1. (Cancelled)

2. (Cancelled)

3. (Original) A method of production of a semiconductor package mounting a capacitor for suppressing fluctuation of a power supply voltage, comprising:

providing an attachment hole passing through a board in a thickness direction and

press-fitting into said attachment hole a capacitor cable comprised of a conductor wire at the core, a high dielectric constant material coaxially covering the conductor wire at a predetermined thickness, and a conductor sheath covering the out circumference of the high dielectric constant material so as to attach the capacitor to said board.

4. (Original) A method of production of a semiconductor package mounting a capacitor for suppressing fluctuation of a power supply voltage, comprising:

providing an attachment hole passing through a board in a thickness direction,

forming a conductor layer at an inner wall of said attachment hole, and,

press-fitting into said attachment hole formed with said conductor layer a capacitor cable comprised of a conductor wire at the core and a high dielectric constant material coaxially covering the conductor wire at a predetermined thickness so as to attach the capacitor to said board.